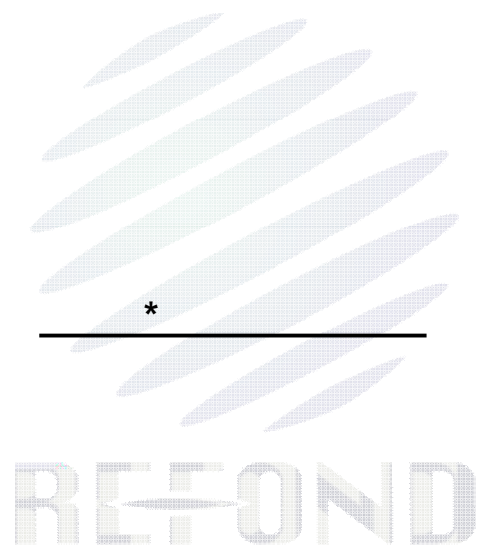


SPECIFICATION



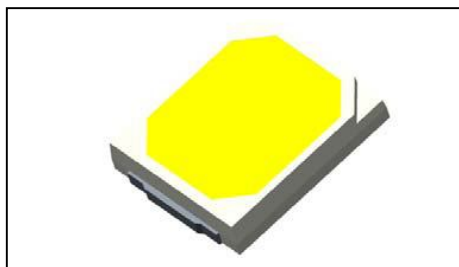


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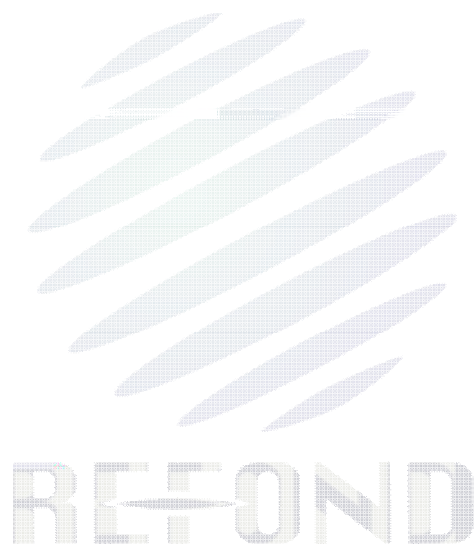
14
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1. Description

1.1



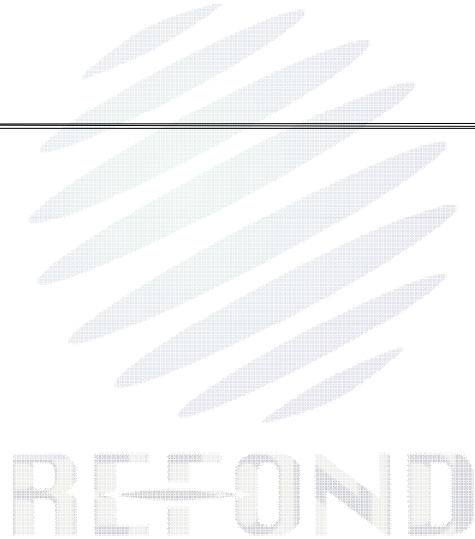
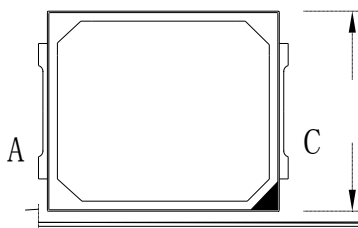
1.2 Features



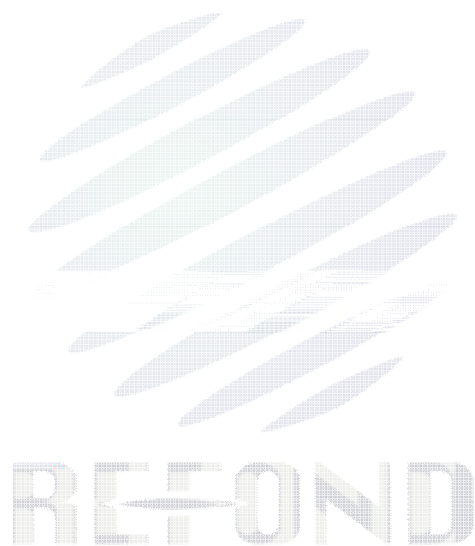
1.3 Application

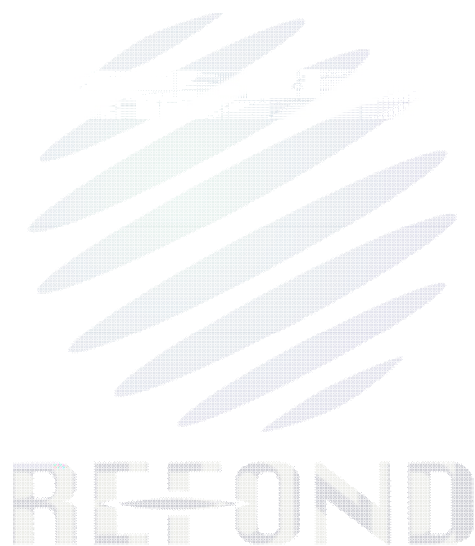
1.4 Product Selection Table

1.5 Package Dimension



1.6 Product Parameters

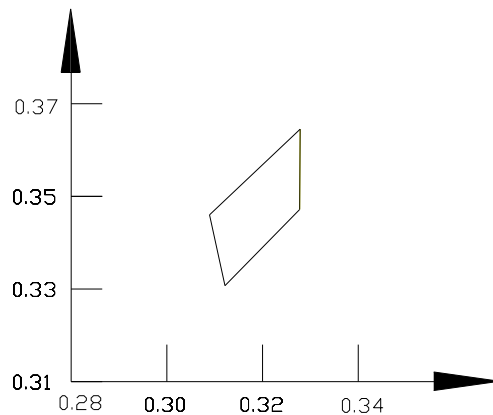
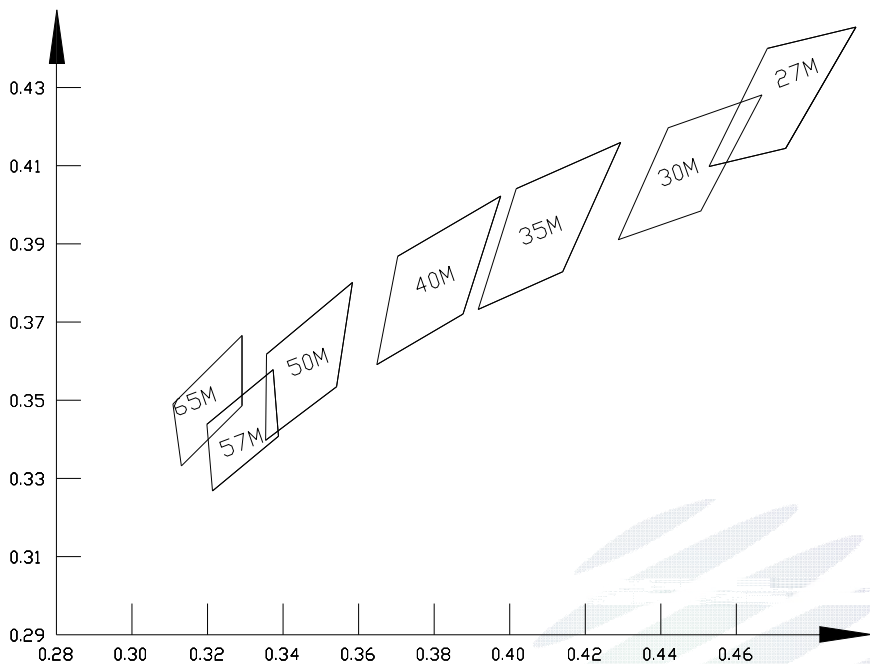




1.7 Bin Range Of Forward Voltage and Luminous Flux (IF=100mA)

BIN (IF=100mA)

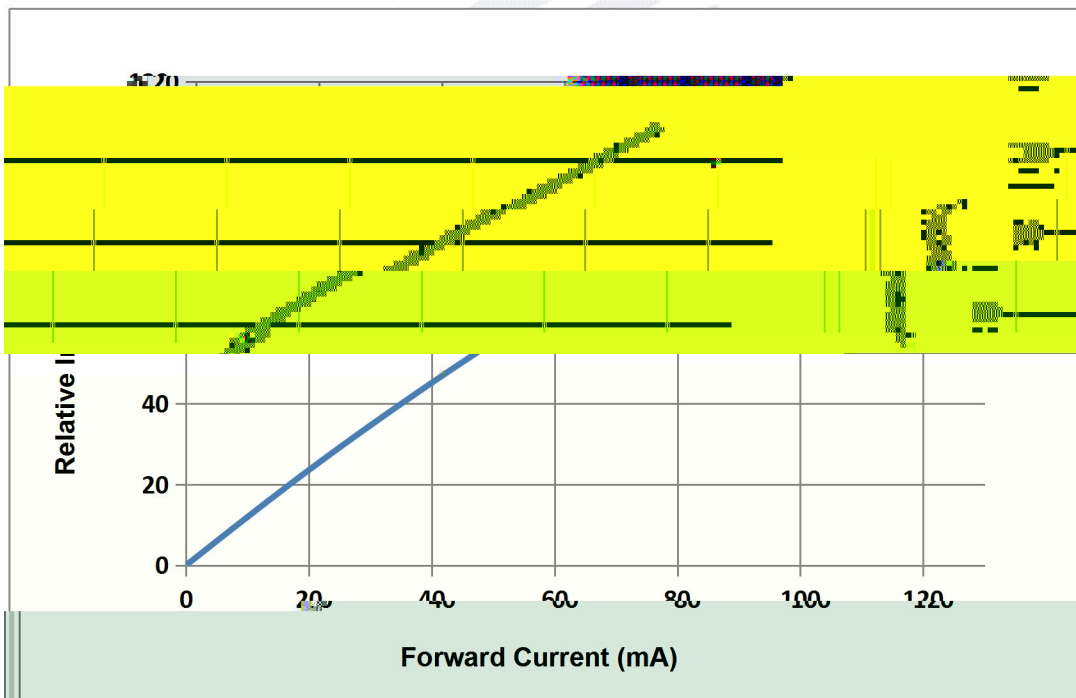
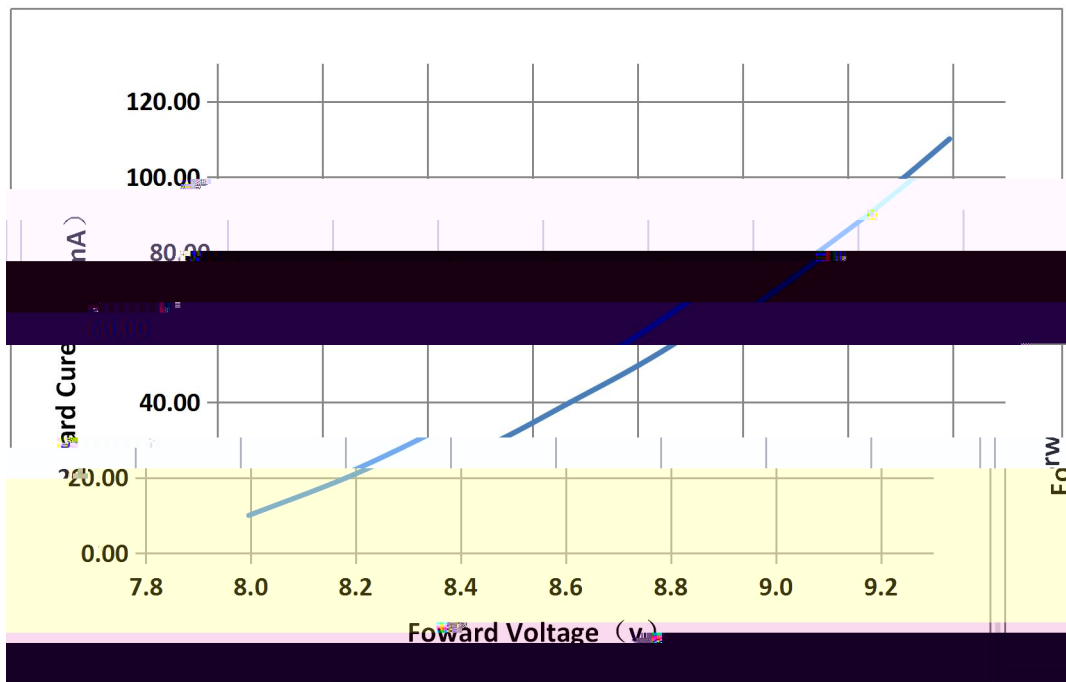


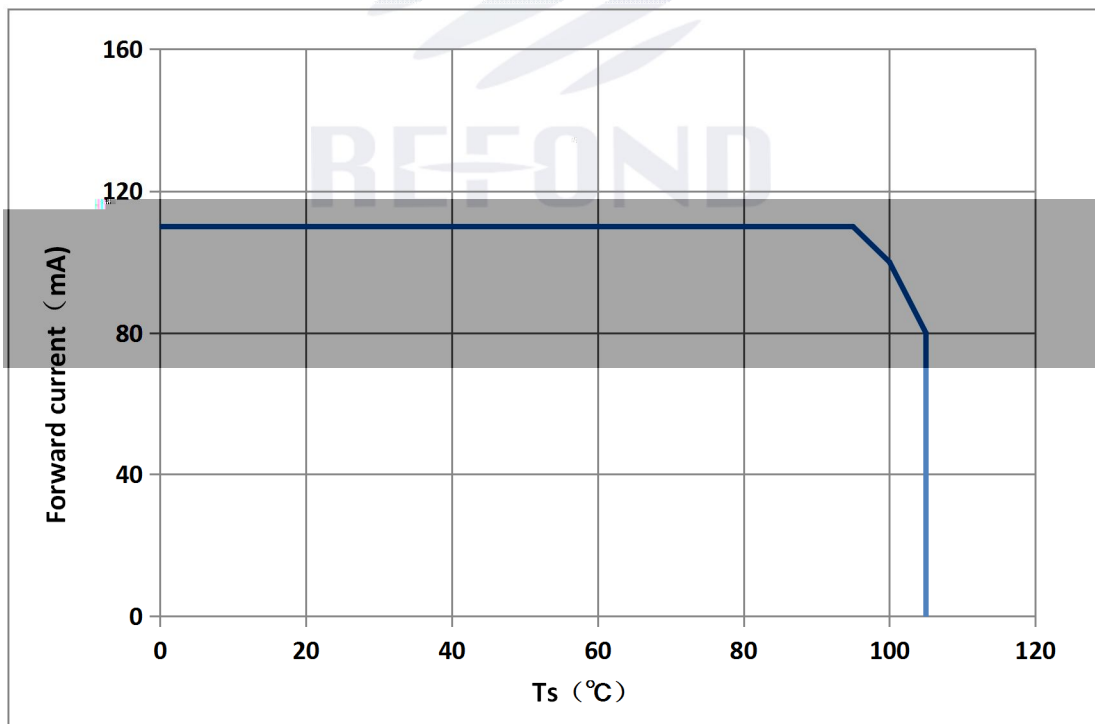
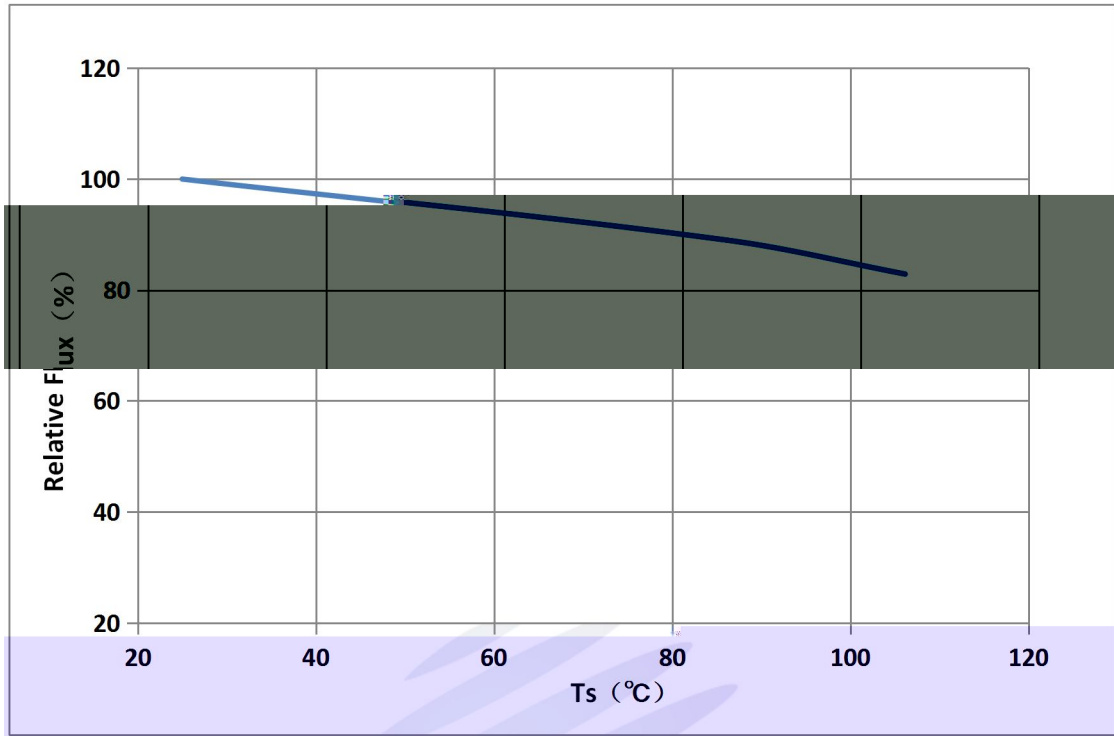


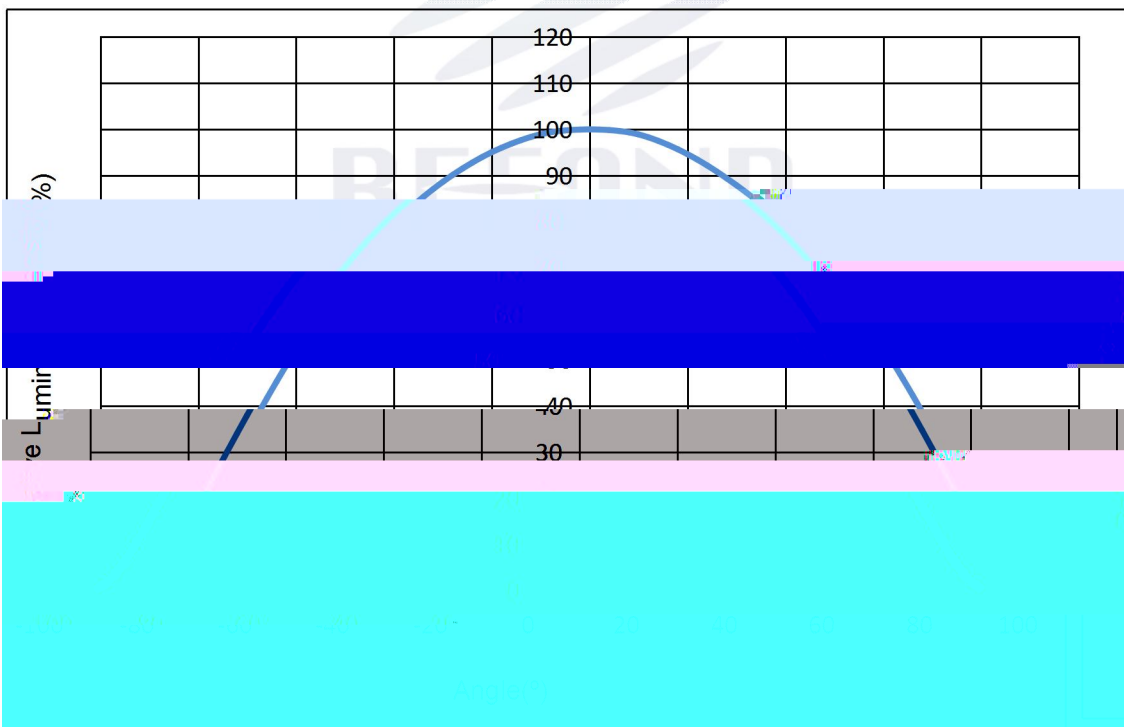
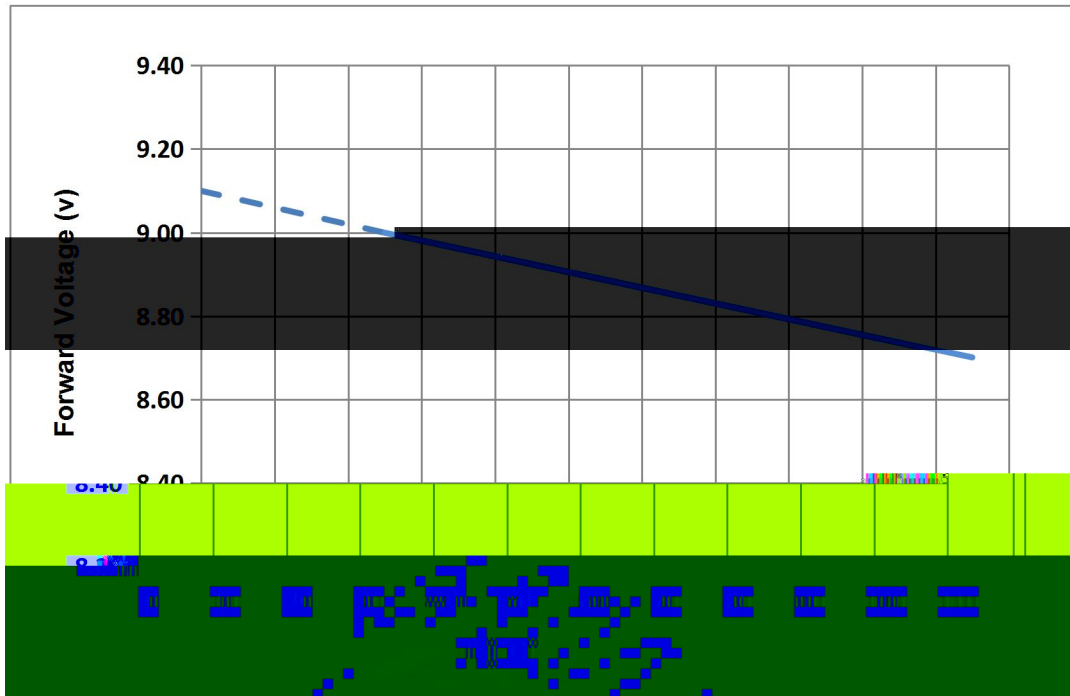
ERP 7-step

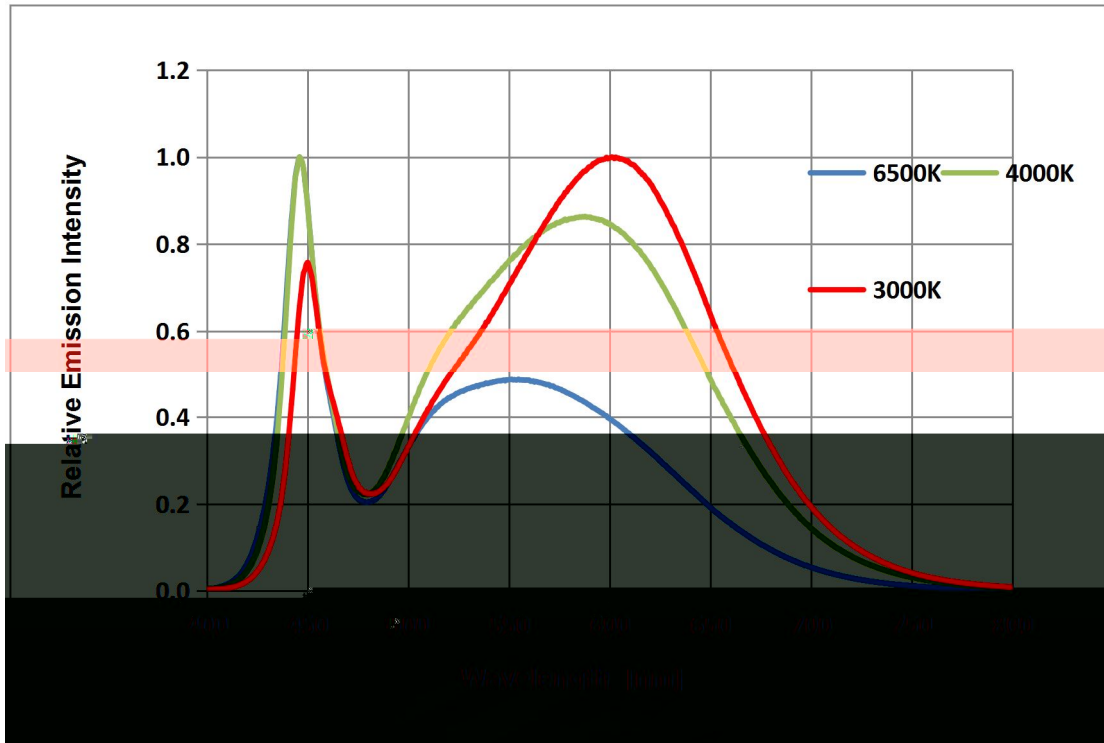
BIN CODE	X1	Y1	X2	Y2	X3	Y3	X4	Y4
27M	0.4528	0.4098	0.4731	0.4144	0.4916	0.4455	0.4682	0.4400
30M								
35M	0.4017	0.4041	0.4294	0.4160	0.4140	0.3829	0.3917	0.3732
40M	0.3704	0.3868	0.3976	0.4022	0.3876	0.3721	0.3648	0.3591
50M	0.3356	0.3618	0.3584	0.3801	0.3542	0.3535	0.3354	0.3397
57M	0.3198	0.3438	0.3374	0.3578	0.3388	0.3408	0.3213	0.3268
65N	0.3121	0.3307	0.3277	0.3472	0.3279	0.3645	0.3089	0.3460
65M	0.3131	0.3332	0.3291	0.3486	0.3291	0.3666	0.3108	0.3490

1.8 Typical optical characteristics curves





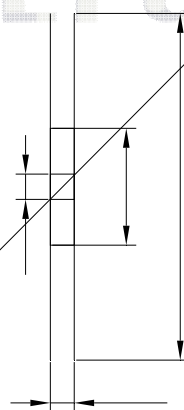
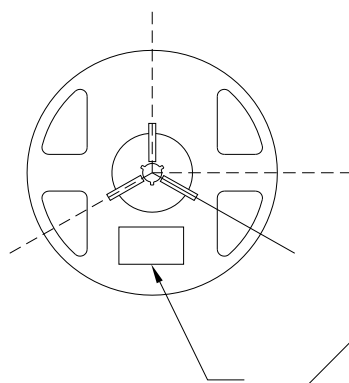
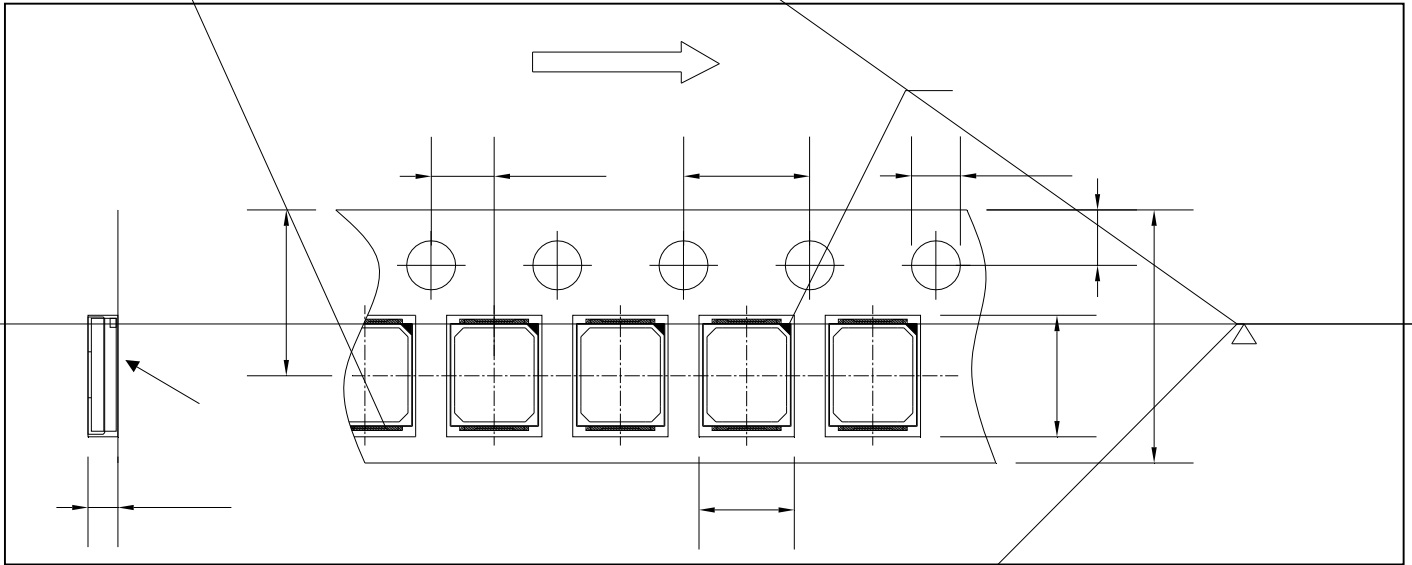




2. Packaging

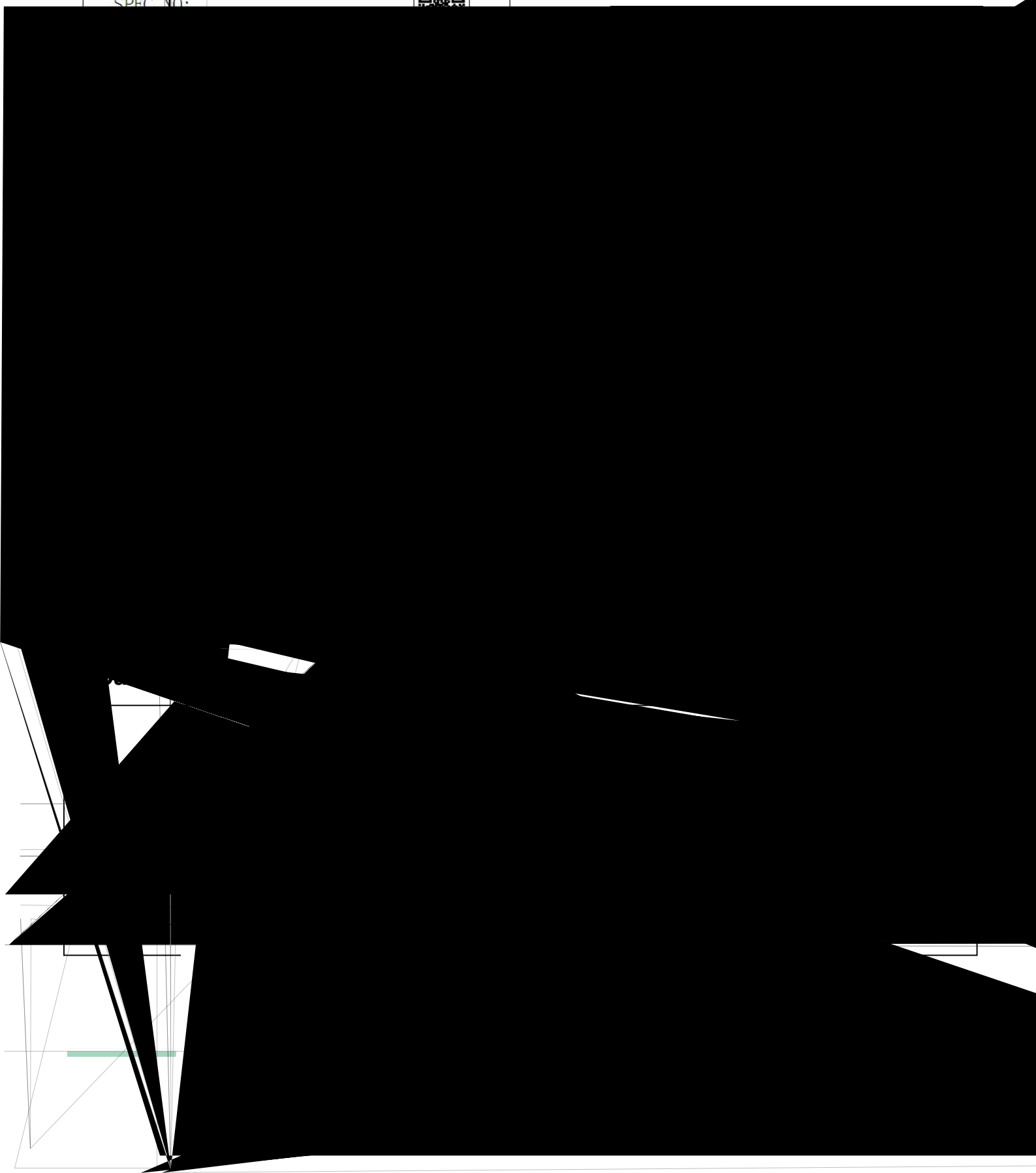
2.1 Packaging Specification

12000pcs





PART NO:
SPEC NO:



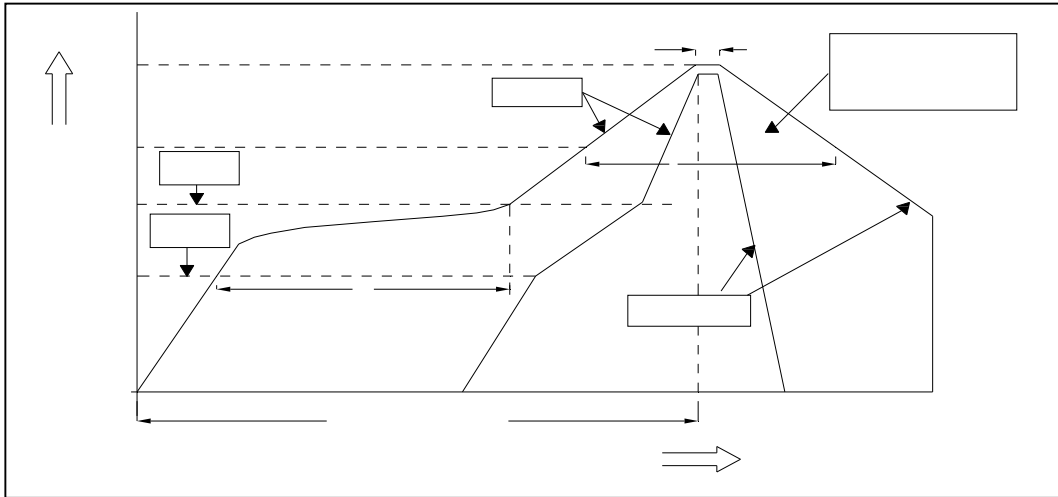
2.4 Reliability Test Items And Conditions

2.5 Criteria For Judging Damage

REFOND

3. SMT Reflow Soldering Instructions SMT

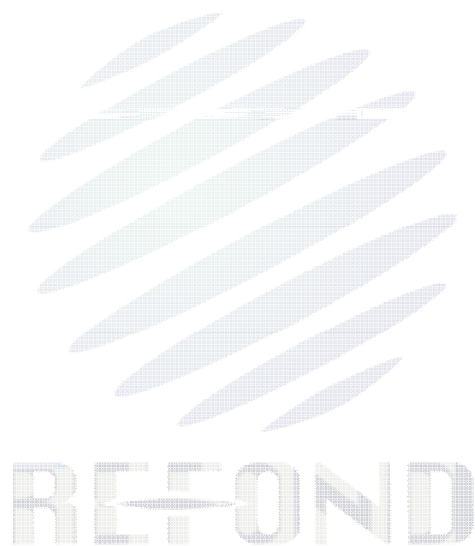
3.1 SMT Reflow Soldering Instructions SMT

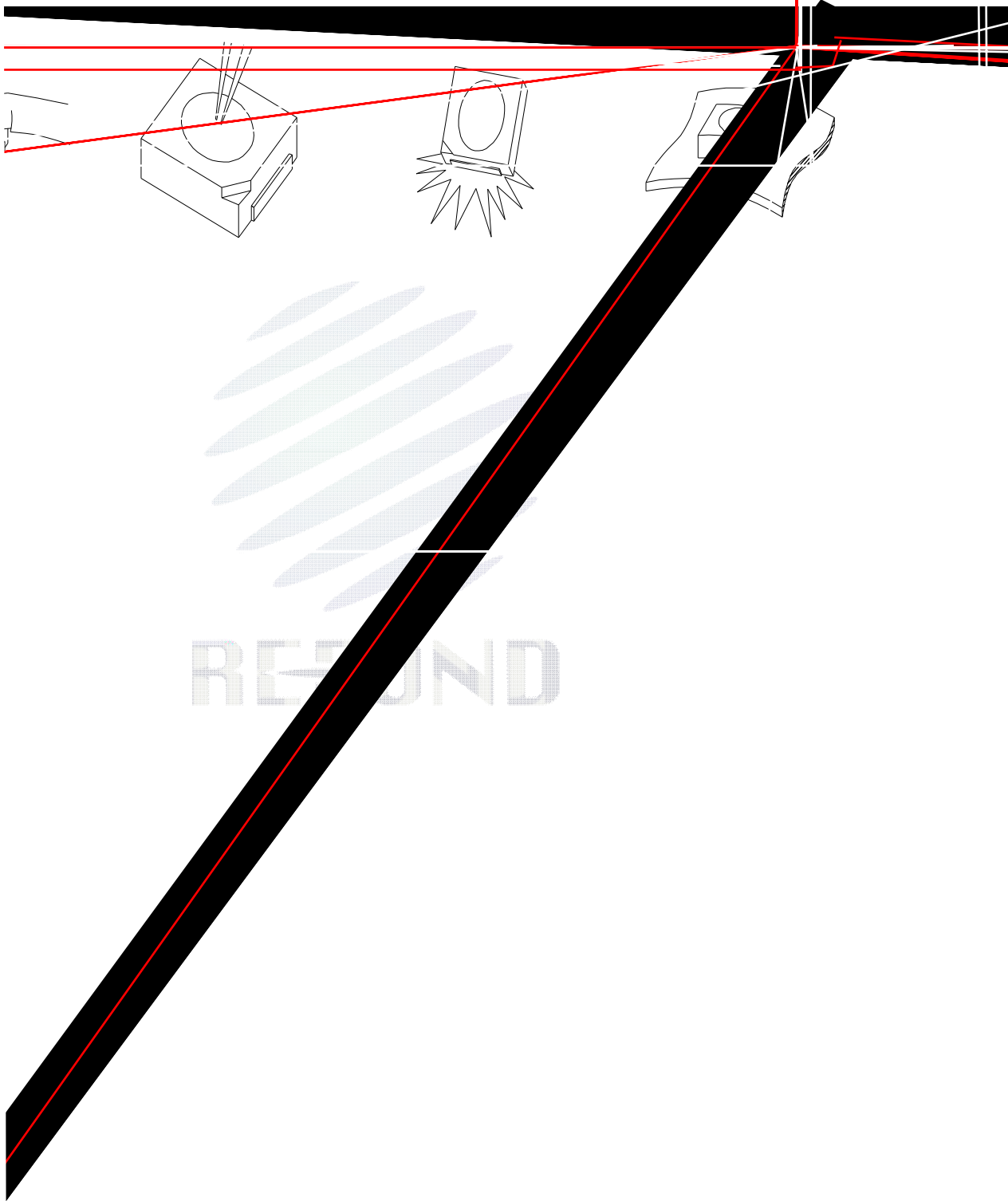




4. Handling Precautions

4.1 Handling Precautions







REFOND



瑞豐光電

